



PATENT ABSTRACTS OF JAPAN

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ENOKI HISAFUMI**(54) RESIN COMPOSITION FOR INSULATING MATERIAL AND INSULATING MATERIAL USING THE SAME****(57) Abstract:**

PROBLEM TO BE SOLVED: To obtain a resin composition for an insulating material and an insulating material having an excellent heat characteristic and electrical characteristic in a semiconductor use.

SOLUTION: The present invention provides the resin composition for the insulating material comprising a component (A) having a hollow structure in which the free volume is 0.001-1,000 nm³ such as a fullerene or a carbon nanotube and a heat resistant resin or its precursor (B) as an essential component, and the insulating material using the same.

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